

FEM INTERFACE (126Y-267977) CLASS 2 BOARD

Proposed stacks			SMALLEST VIA		
1	copper	0.0007	1 thru 6 .008 hole .018 pad	S	M1 - LAYER 1, PRIMARY SIDE (GENERAL ROUTING, 100 OHM TRACES 6.0W )
	dielectric	0.004			
2	copper	0.0007		p	M2- LAYER 2, PLANE (DGND)
	dielectric	0.005			
3	copper	0.0007		S	M3 - LAYER 3, SIGNAL
	dielectric	0.004			
4	copper	0.0007		p	M4 - LAYER 4, PLANE (+3.3V-D)
	dielectric	0.005			
5	copper	0.0007		S	M5 - LAYER 5, SIGNAL (DIFF PAIRS 3.5 W ---5.5 SP)
	dielectric	0.005			
6	copper	0.0007		p	M6 - LAYER 6, PLANE (+5V)
	dielectric	0.005			
7	copper	0.0007		p	M7 - LAYER 7, PLANE (+1.2V, +2.5V-D)
	dielectric	0.005			
8	copper	0.0007		S	M8- LAYER 8, SIGNAL
	dielectric	0.005			
9	copper	0.0007		p	M9 - LAYER 9, PLANE (DGND)
	dielectric	0.004			
10	copper	0.0007		S	M10 - LAYER 10, SIGNAL
	dielectric	0.005			
11	copper	0.0007		p	M11 - LAYER 11, SPLIT PLANE (DGND)
	dielectric	0.004			
12	copper	0.0007		S	M12 - LAYER 12, SECONDARY SIDE (GENERAL ROUTING, 100 OHM TRACES 6.0W)
0.004 ***plus plating (.001)					
thk	0.0634				